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FACSIMILE COVER SHEET

To: Tuan T. Dinh  
Art Unit 2827

Firm: US PATENT AND  
TRADEMARK OFFICE

Fax: 1-703-872-9318

Your ref: 09/970,749

From: Daniel J. Bedell

Date: January 29, 2003

Our ref: FORM 2209 (P139-US)

Pages: Cover + 11

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D Smalls-Logu  
PATENT  
2/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Charles A. MILLER

Application No: 09/970,749

Filed: October 3, 2001

For: MULTIPLE DIE INTERCONNECT SYSTEM

Art Unit: 2827

Examiner:  
Tuan T. Dinh

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REPLY TO THE OFFICE ACTION MAILED 11/19/2002

JAN 29 2003

Assistant Commissioner for Patents  
Washington, D.C. 20231

TECHNOLOGY CENTER 2800

Sir:

Further examination and consideration of this application are requested in view of the following Amendments and Remarks.

AMENDMENTS

In the Claims:

Claim 21, rewrite as follows:

21. (Amended) A multiple die electronic system comprising:  
a substrate having conductors formed thereon,  
a base IC die having a first surface facing the substrate and a second surface parallel to the first surface,  
a first secondary IC die residing between the first surface of the base IC die and the substrate and linked to the first surface of the base IC die through first conductive signal paths, and  
conductive contacts extending between the first surface of the base IC die and the conductors on the substrate for conveying signals between the base IC die and the conductors on the substrate.